

Conference Programme Day 2, Friday June 14

Materials & Processes for the Global Electronics Market - Cost Optimization and Automation for PCB Fabrication

Session 4: Design-Process reliability		Moderator: Christian Behrendt, Ilfa GmbH, DE
09:00-09:20	High Density RDL Technologies for Fan-Out Panel Level Packaging	Fraunhofer IZM, Lars Böttcher, DE
09:20-09:40	PCB Trace Geometry & Effects, "it's a mechanical thing"	HDP User Group International, Martin Cotton, UK
09:40-10:00	Mitigation of Tin Whiskers with ALD (Atomic Layer Deposition) and new solution for PCB processes	Picosun OY, Marko Pudas, FI
10:00-10:20	Be prepared for higher data rates in mobile systems	Ericsson, Stig Källman, SW
10:20-10:40	Critical Material Properties for Millimeter-Wave and High Speed Digital Applications	Rogers Corporation, Stefano Dada, BE
10:40-11:00	Copper Surface Treatment Investigation on High Frequency PCB Electrical Characteristics	Elite Material Co., Ltd, Shannon Juan, TW
11:00-11:20	Panel discussion	
11:20-11:50	30 minutes Coffee break	Table Top & Poster Display Area
Session 5: Automation of Fabrication Technology		Moderator: Hubert Zimmermann, Dyconex, CH
11:50-12:10	Industry 4.0 in the PCB Industry - new standards in the automation of production lines	ASS-SAA Automation GmbH, Frank Tinnefeld, DE
12:10-12:30	InduBond Press technology	Chemplate, Victor Lazarro Gallego, ES
12:30-12:50	New AOI Dimension-6 from Orbotech in combination with the shaping solution Precise-600, demonstrate how these two systems interact with each other to increase the yield of even small series production	Orbotech, Uwe Altmann, BE
12:50-13:10	Smart Molded Structures Bring Surfaces to Life	Tactotek, Outi Rusanen, FI
13:10-13:20	Panel discussion	
13:20-13:30	President closing remarks - End of Conference Day 2	
13:30-14:30	Network Lunch	Hotel restaurant

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